WHM2025AE
2.0 – 2.5 GHz LOW NOISE WIDE BAND AMPLIFIER

Specifications and information are subject to change without notice.

WanTcom, Inc • Phone 01 952 448 6088 • FAX: 01 952 448 7188 • e-mail: sales@wantcominc.com • Web site: www.wantcominc.com
WHM2025AE
2.0 – 2.5 GHz LOW NOISE WIDE BAND AMPLIFIER

Ordering Information

| Model Number | WHM2025AE |

ESD resistance tube of 25 pieces is used for the packing. Contact factory for tape and reel option for higher volume order.

Typical Data

**Passband Performance @ 21 C**

- **S11**
- **S12**
- **S21**
- **S22**

**Noise Figure @ 21C**

**P1dB & IP3 @ 21C**

**Outline, WHM-9**

**Foot Print/Mounting Layout**

- **S11**
- **S12**
- **S21**
- **S22**

Specifications and information are subject to change without notice.

WanTcom, Inc • Phone 01 952 448 6088 • FAX: 01 952 448 7188 • e-mail: sales@wantcominc.com • Web site: www.wantcominc.com
Application Notes:

A. Motherboard Layout

The recommended motherboard layout is shown in diagram of Foot Print/Mounting Layout. Sufficient numbers of ground vias on center ground pad are essential for the RF grounding. The width of the 50-Ohm microstrip lines at the input and output RF ports may be different for different property of the substrate. The ground plane on the backside of the substrate is needed to connect the center ground pad through the vias. The ground plane is also essential for the 50-Ohm microstrip line launches at the input and output ports.

The +5V DC voltage is applied at Pin Vdd. There is a built-in 0.01 UF de-coupling capacitor and no external capacitor is required. For +5V line trace length being longer than 6 inches without a decoupling capacitor, a 0.33 uF de-coupling capacitor, C1, with minimum rating voltage of 10V is needed across the +5V pin to ground. The capacitor must be rated in the temperature range of -55 °C to 100 °C to ensure the entire circuit work in the specified temperature range.

No DC block capacitor is required at input and output RF ports.

B. Assembly

The regular low temperature and none clean solder paste such as SN63 is recommended. The high temperature solder has been used internally for the WHM series amplifier assembly. The melting temperature point of the high temperature solder is around 217 ~ 220 °C. Thus, melting temperature of the solder paste should be below 217 °C for assembling WHM series amplifier on the test board to reduce the possible damage. The temperature melting point of the SN63 solder paste is around 183 °C and is suitable for the assembly purpose.

The SN63 solder paste can be dispensed by a needle manually or driven by a compressed air. Figure 2 shows the example of the dispensed solder paste pattern. Each solder paste dot is in the diameter of 0.005” ~ 0.010” (0.125 ~ 0.250 mm).

For volume assembly, a stencil with 0.004” (0.10 mm) is recommended to print the solder paste on the circuit board.

For more detail assembly process, refer to AN-109 at www.wantcominc.com website.

C. Electrical Testing and Fine Tuning

The amplifier is designed to be fully matched at the input and output ports. Any tuning is not needed. However, when connecting the assembled amplifier to a device such as a SMA connector or a filter, the connecting point or joint point could affect mainly the return loss at the port due to the non-ideal 50-Ohm impedance of the device. By varying the connection feature size such as the solder amount to get the optimum return loss or best matching result at the interface. This fine-tuning has little affect on the other performance such as gain, noise figure, P1dB, or IP3.

During the fine-tuning process, a vector network analyzer can be used to monitoring the return loss at the port while varying the feature size of the joint point. Varying the connection feature size until the optimum return loss is achieved.

*****